

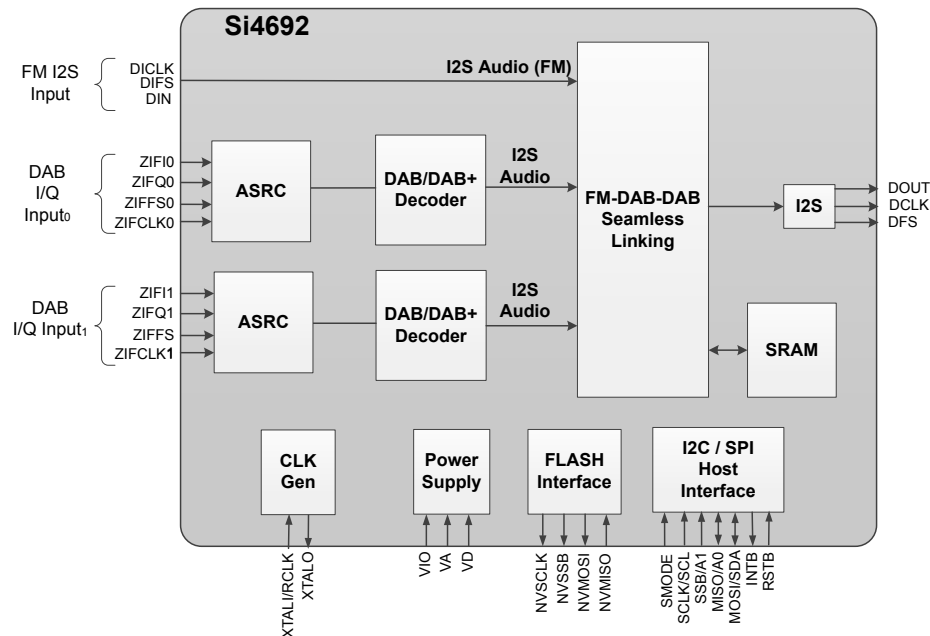
Si4692 Data Short

High-Performance Digital Radio Baseband Processor with Seamless Blending

The Si469x dual DAB/DAB+ radio co-processor provides significant advances in size, power consumption, and performance to enable DAB/DAB+ Radio reception with DAB-DAB-FM seamless blending in automotive infotainment systems and car radios. It is designed to work with the high-performance automotive Si479x family of radio tuners.

Applications

- OEM automotive infotainment systems
- Aftermarket car radio systems



KEY FEATURES

- Dual DAB/DAB+ co-processor (Si4692)
- Single DAB/DAB+ co-processor (Si4690)
- Integrated DAB/DAB/FM (Si4692) and DAB/FM (Si4690) time and level alignment and seamless blending
 - PAD/XPAD outputs available
- FIC decoder
 - Ensemble info
 - Service list
 - Component info
 - Service linking info
- Full support for data services
 - Packet mode
 - Packet mode with Data Groups
 - Enhanced Packet mode
 - MOT, TPEG packet outputs
- No external RAM required for channel decoding or seamless blending
- Flash memory interface for application program load
- Support for Si479xx Zero-IF DAB I/Q at 2.048 MS/s
- Support for I2S audio from third tuner
- Integrated crystal oscillator
- Reference clock input
- SPI, I2C control interfaces
- LGA 72-pin, 10 x 10 x 1 mm
- Pb-free/RoHS compliant
- AEC-Q100 qualified

1. Pin Descriptions

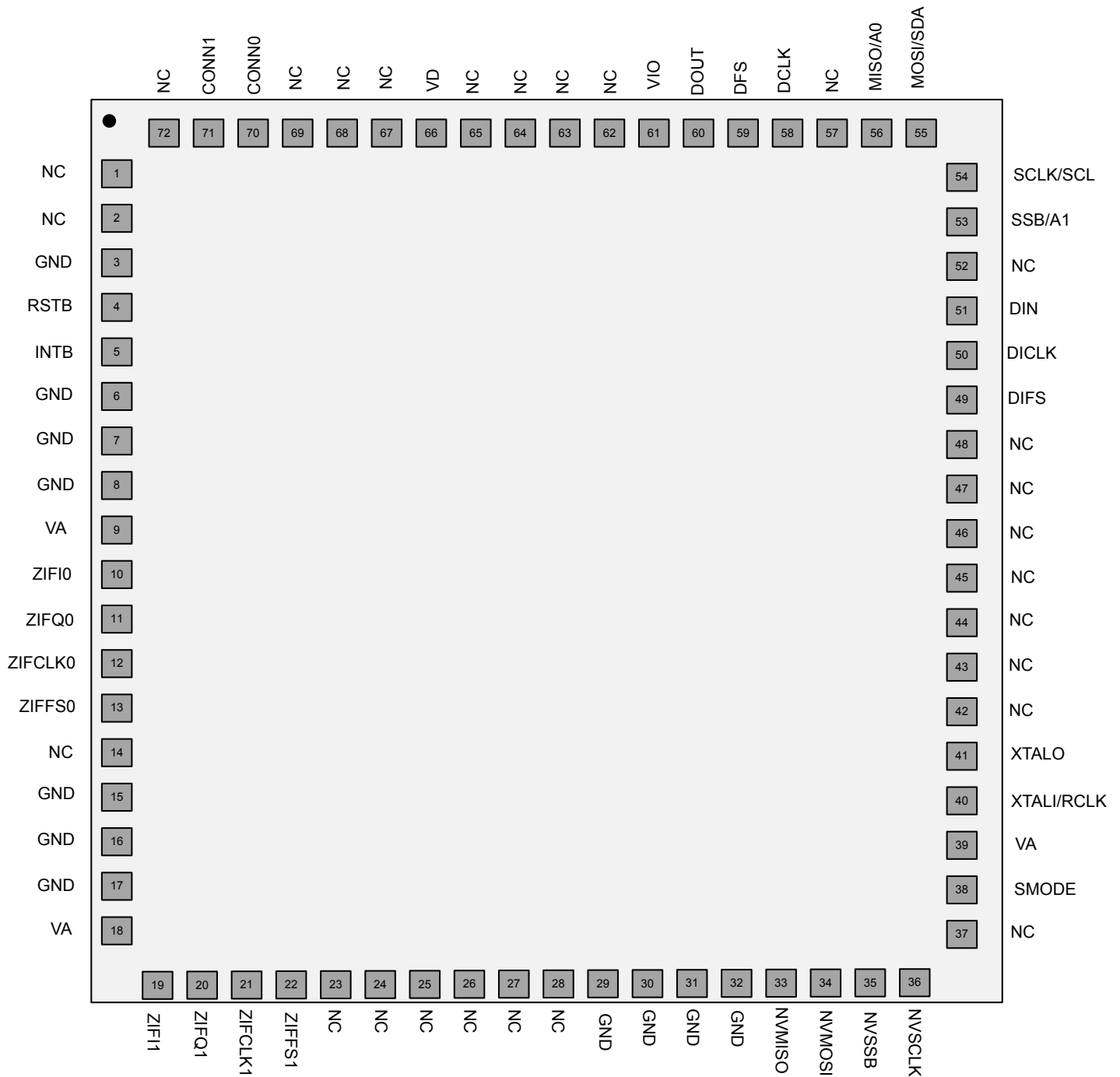


Figure 1.1. Si4692 Pinout Diagram

2. Package Outline

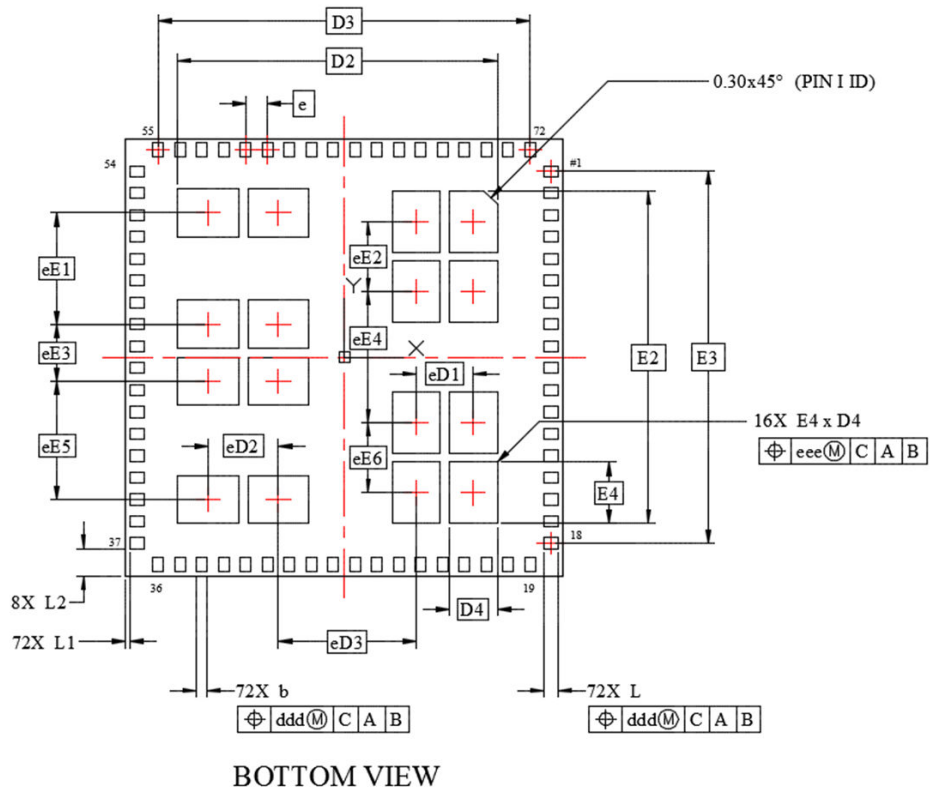
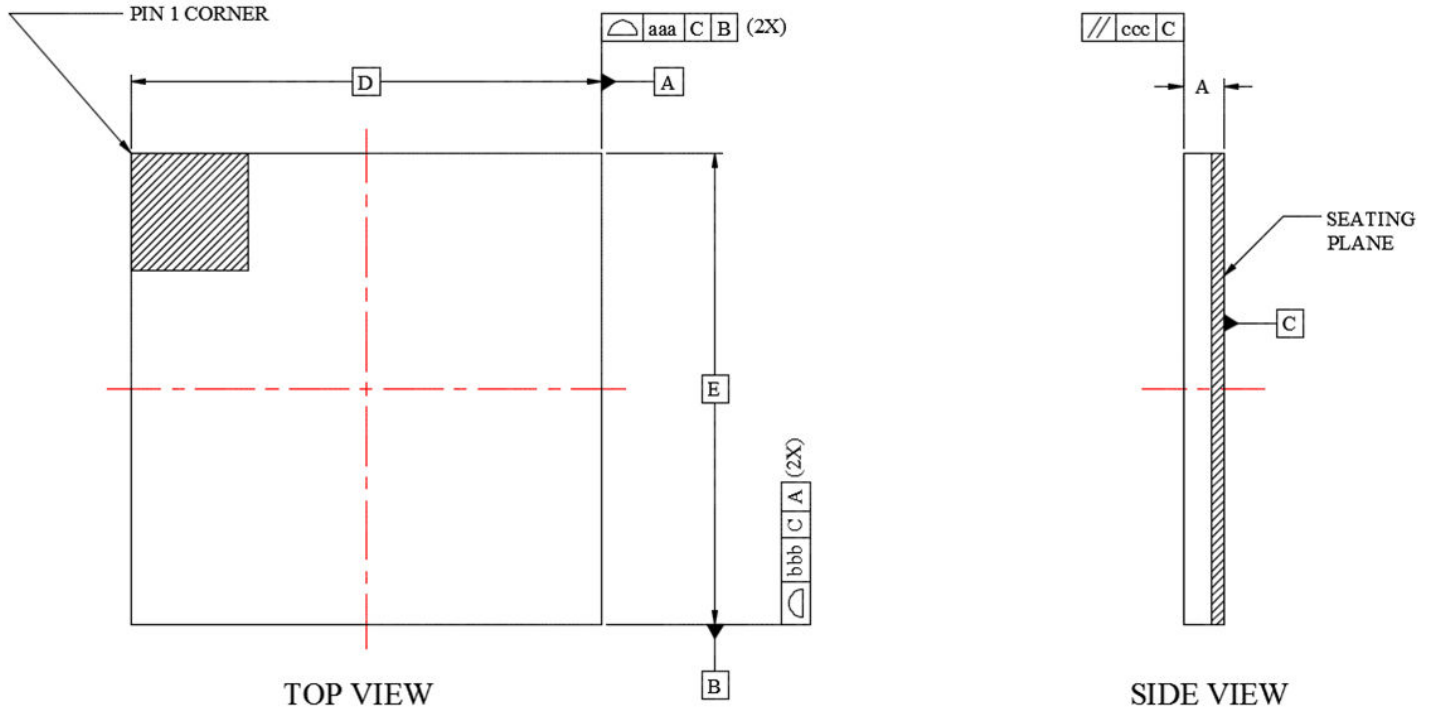


Figure 2.2. 10 x 10 mm 72-Pin LGA

Table 2.1. Package Dimensions

Dimension	Min	Nom	Max
A	1.00	1.08	1.20
b	0.15	0.25	0.35
D	10.0 BSC		
D2	7.20	7.30	7.40
D3	8.50 BSC		
D4	1.00	1.10	1.20
e	0.50 BSC		
E	10.0 BSC		
E2	7.50	7.60	7.70
E3	8.50 BSC		
E4	1.30	1.40	1.50
L	0.225	0.325	0.425
L1	0.05	0.10	0.15
L2	0.575	0.625	0.675
eD1	1.30 BSC		
eD2	1.60 BSC		
eD3	3.15 BSC		
eE1	2.55 BSC		
eE2	1.60 BSC		
eE3	1.30 BSC		
eE4	3.00 BSC		
eE5	2.70 BSC		
eE6	1.60 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.10		
ddd	0.10		
eee	0.10		

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
3. This drawing conforms to the JEDEC Solid State Outline MO-220.
4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.